THIN-FILM MATERIALS

32 N Gould St., Sheridan, WY 82801, USA
Tel.: +1 (786) 825 8645
WhatsApp: Keyue Advanced Materials
Email: sales@thinfilmmaterials.com
Website: www.thinfilmmaterials.com

Certificate of Analysis (CoA)

Mar. 12, 2026

Product Name: Manganese Telluride Sputtering Target, ST0325
Chemical Formula: MnTe
Composition: Mn : Te = 1 : 1 (atomic ratio)
Purity: 99.9% (3N)
Dimensions: Ø50.8 mm × 2.0 mm
Backing Plate: Properly bonded to Copper backing plate, 3 mm thick
Quantity: 1 pc
Lot Number: CSJM-260312004
Manufactured by: Thin-Film Materials

Physical Description

- Appearance: Dark gray dense target
- Crystal Structure: Hexagonal (NiAs-type)
- Fabrication: Powder metallurgy, sintered and bonded
- Typical Density: ≥95% of theoretical

Theoretical Stoichiometric Composition (Mass %)

(Atomic ratio: Mn : Te = 1 : 1)

Element	Symbol	Mass %
Manganese	Mn	~28.1%
Tellurium	Te	~71.9%

Balance: MnTe

Chemical Composition (by ICP-OES / XRF)

Element	Symbol	Specification
Manganese	Mn	1.0 (atomic ratio)

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Element	Symbol	Specification
Tellurium	Te	1.0 (atomic ratio)
Total Metallic Impurities	–	<1000 ppm
Individual Impurity (each)	–	<200 ppm

Bonding Information

- Bonding Method: Indium or elastomer bonding (standard sputtering bonding process)
- Backing Plate Material: OFHC Copper
- Backing Plate Thickness: 3 mm

Handling & Storage

- Store in dry and clean environment.
- Avoid mechanical shock to prevent cracking.
- Handle with gloves to avoid surface contamination.

Declaration

The material described above has been manufactured, inspected, and released in accordance with internal quality control procedures and complies with the specifications stated herein.

Authorized Signature:

Inspection Certificate by: **Nancy Liu**

Approver by: **Chen Qiang** chen Qiang